



Main page > Repair Equipment > Soldering Equipment > Platform reballing BGA > AMAOE Mbga-B18 BGA reballing platform with stencils for Qualcomm CPU Snapdragon 855/845/SDM845/SM8150/RAM556

## AMAOE Mbga-B18 BGA reballing platform with stencils for Qualcomm CPU Snapdragon 855/845/SDM845/SM8150/RAM556

Product ID: 22954

Price: **45.00 EUR**

Product weight: **1.00 kg**

### Description:

AMAOE Mbga-B18 BGA reballing platform with stencils for Qualcomm CPU Snapdragon 855/845/SDM845/SM8150/RAM556- Reballing platforms are high-quality products that enable precise re-creation of balls connecting the upper and lower parts of the motherboard and for removing glue. Made of high-quality synthetic stone, resistant to high temperatures and quickly cooling down. Platforms equipped with very strong magnets that prevent movement during soldering work using templates / reballing sieves.

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